

**DECLARATION - USA PATENT APPLICATION**

As a below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name;

I believe I am an original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled THERMOSTABLE L-ARABINOSE ISOMERASE AND PROCESS FOR PREPARING D-TAGATOSE; the specification of which was filed on June 20, 2003 as Application Serial No. 10/600,689

I hereby state that I have reviewed and understand the contents of the above identified specification, including the claims, as amended by any amendment referred to above;

I acknowledge the duty to disclose information which is material to the patentability of this application in accordance with Title 37, Code of Federal Regulations, § 1.56;

I hereby claim foreign priority benefits under Title 35, United States Code, §§ 119 or 365 of any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) listed below and have also identified below any foreign application(s) for patent, design or inventor's certificate or any PCT international application(s) designating at least one country other than the United States of America filed for the same subject matter having a filing date before that of the application(s) of which priority is claimed:

PRIOR FOREIGN APPLICATIONS

COUNTRY	APPLICATION NUMBER	DATE OF FILING	PRIORITY CLAIMED UNDER 37 U.S.C. § 119(b)
Korea	2000/80608	December 22, 2000	Yes
Korea	2000/80711	December 18, 2001	Yes

I hereby claim the benefit under Title 35, United States Code, §§ 120 or 365 of any United States application(s) listed below, and insofar as the subject matter of each of the claims of this application is not disclosed in the prior United States application in the manner provided by the first paragraph of Title 35, United States Code § 112, I acknowledge the duty to disclose information which is material to patentability as defined in Title 37, Code of Federal Regulations, § 1.56, which became available between the filing date of the prior application and the national or PCT international filing date of this application:

PRIOR U.S.A. APPLICATION

APPLICATION NUMBER	DATE OF FILING	PRIORITY CLAIMED UNDER 37 U.S.C. § 365(c)
PCT/KR01/02243	December 22, 2001	Yes

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I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful, false statements may jeopardize the validity of the application or any patent issued thereon.

Full name of first inventor: PYUN, Yu Ryang

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Full name of fifth inventor: LEE, Yoon Hee

Dated: October 21, 2003 Inventor's signature *Yoon Hee Lee*
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